REMARKS

Claims 1-4 and 20 are pending.

Examiner Kim is thanked for the courtesies extended to applicants' undersigned attorney during the personal interview conducted on April 25, 2006. Applicants' separate record of the substance of that interview is incorporated into the following discussion.

Claims 1-4 and 20 were rejected under 35 USC §103(a) as being unpatentable over Hikita et al. in view of Kobayashi et al. Favorable reconsideration of this rejection is earnestly solicited.

The claimed method is directed to mounting an electronic component on a substrate. Claim 1 requires placing the electronic component on the substrate with a solid support interposed between the electronic component and the substrate so as to space a terminal conductor of the electronic component from a corresponding terminal pad on the substrate, melting a conductive bonding material on the terminal pad, and thereafter melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the conductive material melting on the corresponding terminal pad. Claim 20 which depends from claim 1, specifies that the electronic component drops towards the substrate based on its own weight in response to melting of the solid support. The combination of references fails to teach or suggest the features set forth in the pending claims.

The Office Action cited Hikita et al. as teaching a process which allegedly includes melting the solid support so as to move down the electronic component toward the substrate. The Office Action further contends that Hikita et al. merely does not teach melting the conductive bonding material on the terminal pad prior to contacting the terminal conductor with the conductive bonding material. Kobayashi et al. is cited for allegedly rendering this feature obvious.

Hikita et al., however, teaches compressing and deforming of an anisotropic conductive film 24. Mounting occurs by curing and setting the conductive film 24 by applying heating or the like. Thus, this heating is for curing, not melting as required by the present claims. Hikita et al. merely describes that the anisotropic conductive film 24 is cured and set by applying heating or the like by keeping the depressing state (see column 5, lines 65 through column 6, line 1).

Accordingly, the combination of Hikita et al. and Kobayashi et al. does not teach melting a conductive bonding material on the terminal pad, and thereafter melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the conductive bonding material melting on the corresponding terminal pad, as required by claim 1. Furthermore, the combination of references fails to teach or suggest that the electronic component drops toward the substrate based on its own weight in response to melting of the solid support.

At the interview, Examiner Kim had indicated that the arguments appear persuasive. Favorable reconsideration of the rejection is thereby earnestly solicited.

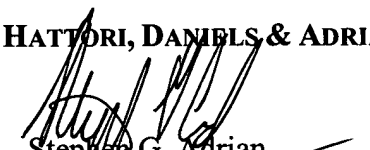
For at least the foregoing reasons, the claimed invention distinguishes over the cited art and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

Should the Examiner deem that any further action by applicants would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone applicants' undersigned attorney.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP



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